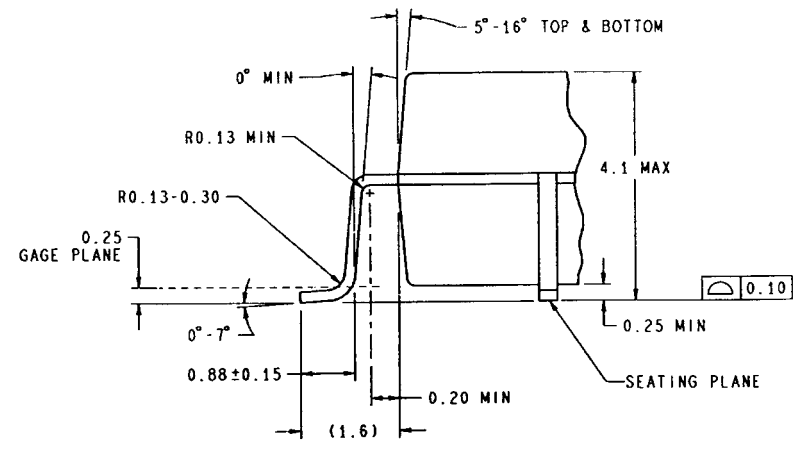
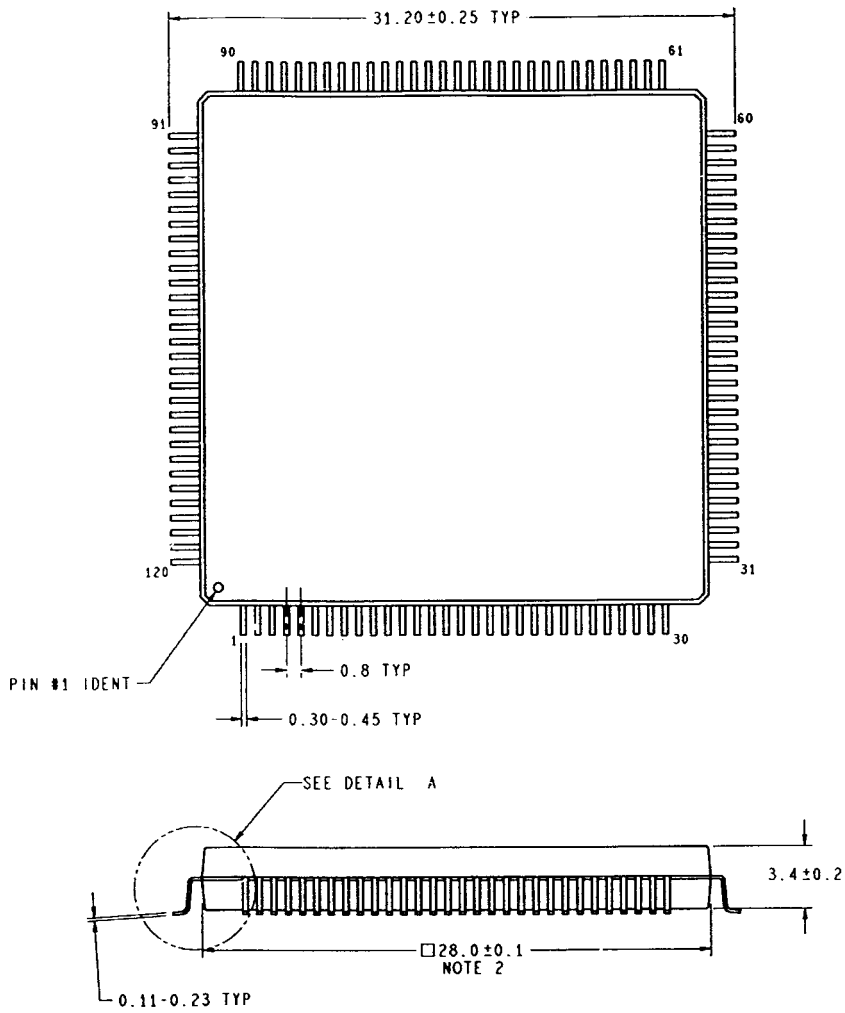


REVISIONS			
LTR	DESCRIPTION	E.C.N.	DATE
C	REVISE AND REDRAW PER JEDEC MS-022.	11040	07/13/95



DETAIL A
TYP, SCALE: 17X

DIMENSIONS ARE IN MILLIMETERS

NOTES: UNLESS OTHERWISE SPECIFIED

- STANDARD LEAD FINISH:
7.62 MICROMETERS MINIMUM SOLDER PLATING (85/15)
THICKNESS ON COPPER.
- DIMENSION DOES NOT INCLUDE MOLD PROTRUSION.
MAXIMUM ALLOWABLE MOLD PROTRUSION 0.25mm PER SIDE.
- REFERENCE JEDEC STANDARD MS-022, VARIATION DA-1,
DATED FEB/95.

APPROVALS	DATE	National Semiconductor			
DRN: D.E. Grady	01/13/95	2900 Semiconductor dr., Santa Clara, CA 95052-8090			
DTG. CHK: [Signature]	2/15/95	POFP, JEDEC METRIC, (S), 28 X 28 X 3.4mm, 120 LEAD			
ENGR. CHK: H.J. Kim	7/17/95				
PROJECTION		SCALE	SIZE	DRAWING NUMBER	REV
[Symbol]		N/A	C	MKT-VUZ120A	C
DO NOT SCALE DRAWING				SHEET 1 of 1	